

RoHS
Compliant

Specifications

Dice material : InGaN/Sapphire
Emmiting Colour : Blue
Lens colour : Water clear
Dominant Wavelength : 465nm
Viewing angle : 130°
Luminous intensity (IV) : 100mcd

Absolute Maximum Ratings at Ta=25°C

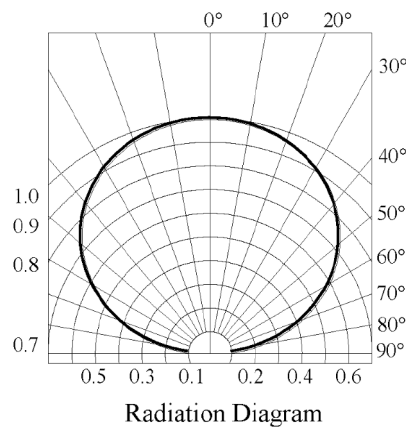
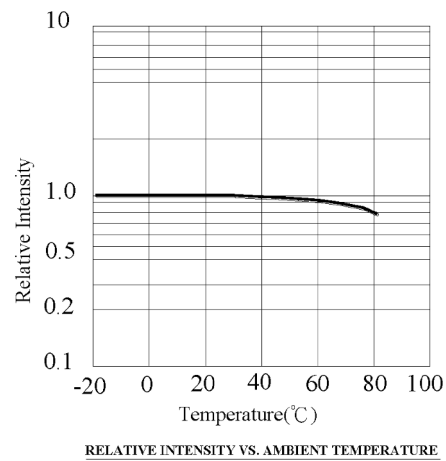
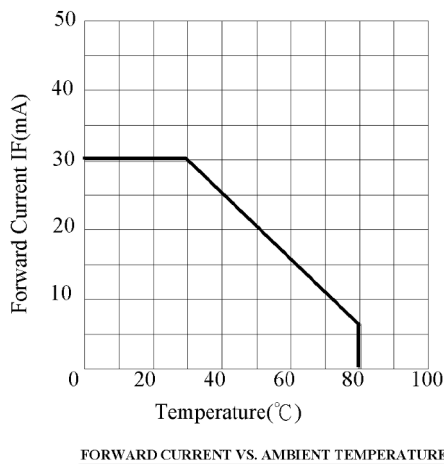
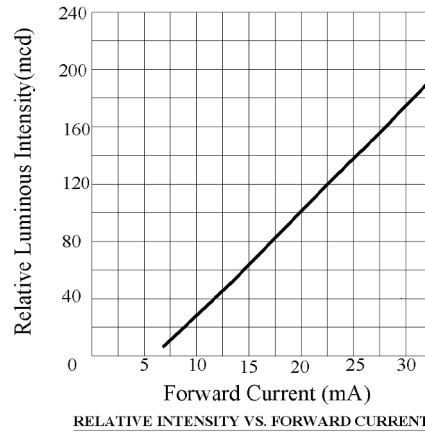
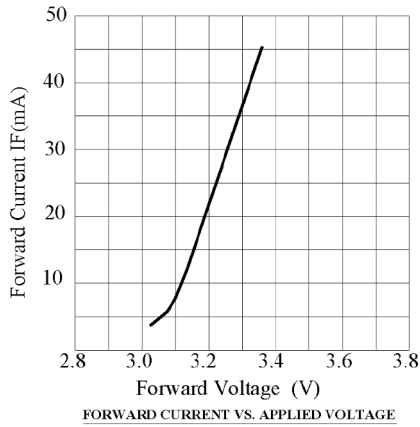
Parameter	Symbol	Rating	Unit
Power Dissipation	PD	120	mW
D.C Forward current	If	30	mA
Reverse Voltage	Vr	5	V
Operating Temperature	Top	-30 to +80	°C
Storage Temperature	Tstg.	-40 to +85	°C
Peak Current (1/10Duty Cycle,0.1ms Pulse Width.)	If (peak)	80	mA
Soldering Temperature	Tsol	Reflow Soldering: 260°C for 10 sec.	
Electric Static Discharge	ESD	6000	V

Electrical and Optical Characteristics

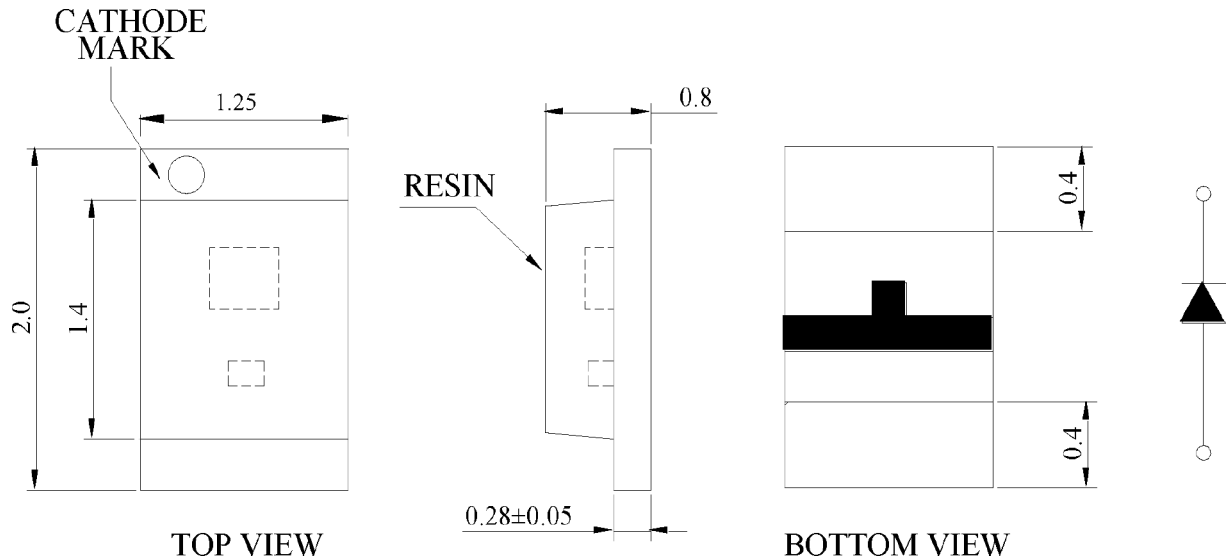
Parameter	Symbol	Condition	Min.	Typ.	Max.	Unit
Luminous Intensity	Iv	If=20mA	51.6	100		mcd
Forward Voltage	Vf	If=20mA		3.2	4	V
Peak Wavelength	λ_p					
Dominant Wavelength	λ_d	If=20mA		465		nm
Reverse Current	Ir	Vr=5V			50	μ A
Viewing Angle	2 θ 1/2	If=20mA		130		deg
Spectrum Line Halfwidth	$\Delta\lambda$	If=20mA		26		

Typical Electrical/Optical Characteristic Curves

(25°C Ambient Temperature Unless Otherwise Noted)



Dimensions



Tolerance is ± 0.1 mm unless otherwise noted.

Dimensions : Millimetres

Precautions in use:

Storage

Recommend storage environment:

Temperature: 5°C to 30°C (41°F to 86°F)

Humidity: 60% RH Max.

Use within 7 days after opening of sealed vapor/ESD barrier bags.

If the moisture absorbent material (silica gel) has faded away or the LEDs have exceeded the storage time, baking treatment should be performed using the following conditions. Baking treatment : 60±5°C for 24 hours.

Fold the opened bag firmly and keep in dry environment.

Soldering

Reflow Soldering

Recommend use of upper and lower heater type reflow furnace.

260°C Max for up to 5 seconds, one time only.

Pre-heat is 150°C Max for up to 2 minutes Max.

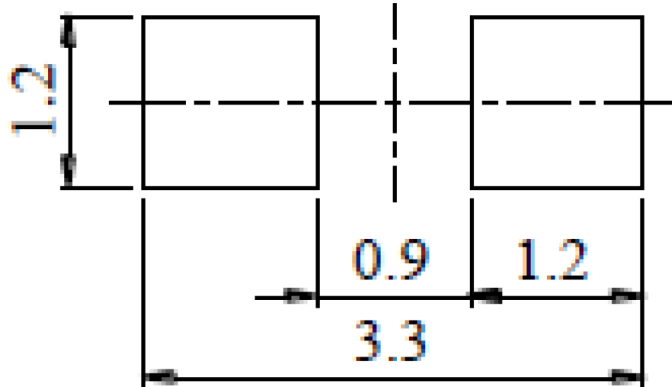
In case of screen-printing, keep metal mask thickness between 0.2mm and 0.3mm.

Cleaning

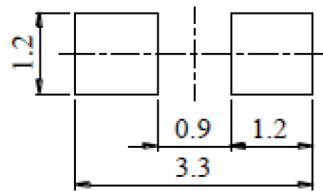
Surface condition of this device may change when organic solvents such as trichloroethylene or acetone were applied.

Avoid using organic solvent. Recommend ultrasonic method 300W Max.

Reflow Temp/Time



Reflow Soldering Pad Dimensions



Part Number Table

Description	Part Number
Chip LED, Blue, 465nm, 130°, 100mcd, Surface Mount	MP008261

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